

Microprocessor Supervisory Circuit

ADM1232

FEATURES

Superior Upgrade for MAX1232 and Dallas DS1232 Low Power Consumption (500 µA max) Adjustable Precision Voltage Monitor with +4.5 V and +4.75 V Options

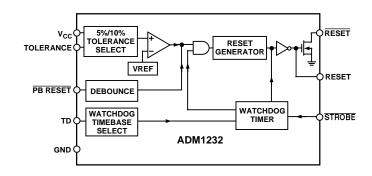
Adjustable STROBE Monitor with 150 ms, 600 ms or 1.2 sec Options

No External Components

APPLICATIONS

Microprocessor Systems
Portable Equipment
Computers
Controllers
Intelligent Instruments
Automotive Systems
Protection Against Damage Caused by µP Failure

FUNCTIONAL BLOCK DIAGRAM



GENERAL DESCRIPTION

The ADM1232 is a superior, pin-compatible upgrade for the MAX1232 and the DS1232LP and DS1232. The Analog Devices ADM1232 is a microprocessor monitoring circuit that can monitor:

- 1. Microprocessor Supply Voltage.
- 2. Whether a Microprocessor has locked-up.
- 3. An External Interrupt.

The ADM1232 is available in four different packages:

- 1. The ADM1232ARM in an 8-lead microSOIC (RM-8).
- 2. The ADM1232AN in an 8-lead PDIP (N-8).
- 3. The ADM1232ARW in a 16-lead wide SOIC (R-16).
- 4. The ADM1232ARN is an 8-lead narrow SOIC (R-8).

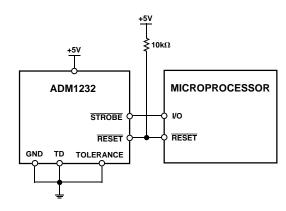


Figure 1. Typical Supply Monitoring Application

$\begin{cases} ADM1232-SPECIFICATIONS & (V_{CC} = Full \ Operating \ Range, \ T_A = T_{MIN} \ to \ T_{MAX} \ unless \ otherwise \ noted) \end{cases}$

Parameter	Min	Тур	Max	Units	Test Conditions/Comments
TEMPERATURE	-40		+85	°C	$T_A = T_{MIN}$ to T_{MAX}
POWER SUPPLY Voltage Current	4.5	5.0 20 200	5.5 50 500	V μΑ μΑ	$V_{IL},V_{IH}=CMOSLevels$ $V_{IL},V_{IH}=TTLLevels$
STROBE AND PB RESET INPUTS Input High Level Input Low Level	2.0 -0.3		V _{CC} + 0.3 +0.8	V V	
INPUT LEAKAGE CURRENT (STROBE, TOLERANCE) TD	-1.0	1.6	+1.0	μ Α μ Α	
OUTPUT CURRENT RESET RESET, RESET	8 -8	10 -12		mA mA	When V_{CC} Is at 4.5 V–5.5 V When V_{CC} Is at 4.5 V–5.5 V
OUTPUT VOLTAGE RESET/RESET RESET/RESET High Level RESET/RESET Low Level	V _{CC} - 0.5	V _{CC} - 0.1	0.4	V V V	While sourcing less than 500 μA , RESET remains within 0.5 V of $V_{\rm CC}$ on power-down until $V_{\rm CC}$ drops below 2.0 V. While sinking less than 500 μA , RESET remains within 0.5 V of GND on power-down until $V_{\rm CC}$ drops below 2.0 V.
1 V OPERATION RESET Output Voltage RESET Output Voltage		V _{CC} - 0.1		V V	While Sourcing Less than 50 μA While Sinking Less than 50 μA
V _{CC} TRIP POINT 5% 10%	4.5 4.25	4.62 4.37	4.74 4.49	V V	$\begin{aligned} & \text{TOLERANCE} = \text{GND} \\ & \text{TOLERANCE} = \text{V}_{\text{CC}} \end{aligned}$
CAPACITANCE Input (STROBE, TOLERANCE) Output (RESET, RESET)			5 7	pF pF	$T_A = +25^{\circ}C$ $T_A = +25^{\circ}C$
PB RESET Time Delay	20 1	4	20	ms ms	PB RESET Must Be Held Low for a Minimum of 20 ms to Guarantee a Reset
RESET ACTIVE TIME STROBE Pulse Width Timeout Period	70 62.5 250 500	150 600 1200	250 1000 2000	ns ns ms ms	$TD = 0 V$ $TD = Floating$ $TD = V_{CC}$
V _{CC} Fall Time Rise Time	10 0			μs μs	Guaranteed by Design Guaranteed by Design
V_{CC} FAIL DETECT TO RESET OUTPUT DELAY RESET AND RESET Are Logically Correct	252	040	50	μs	After V _{CC} Falls Below the Set Tolerance Voltage (Figure 5)
	250	610	1000	ms	After V _{CC} Rises Above the Set Tolerance Voltage

Specifications subject to change without notice.

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ADM1232

ABSOLUTE MAXIMUM RATINGS*

RM-8

*Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those listed in the operational sections of this specification is not implied. Exposure to absolute maximum ratings for extended periods of time may affect device reliability.

ORDERING GUIDE

Model	Temperature Range	Package Options*
ADM1232ARM	-40°C to +85°C	RM-8
ADM1232AN	-40°C to +85°C	N-8
ADM1232ARW	-40°C to +85°C	R-16
ADM1232ARN	-40°C to +85°C	R-8

^{*}N= Plastic DIP; R = Small Outline; RM = microSOIC.

CAUTION

ESD (electrostatic discharge) sensitive device. Electrostatic charges as high as 4000 V readily accumulate on the human body and test equipment and can discharge without detection. Although the ADM1232 features proprietary ESD protection circuitry, permanent damage may occur on devices subjected to high energy electrostatic discharges. Therefore, proper ESD precautions are recommended to avoid performance degradation or loss of functionality.

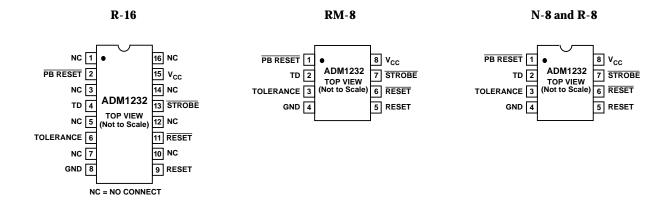


REV. B _3_

PIN FUNCTION DESCRIPTIONS

Mnemonic	Function
PB RESET	Push Button Reset Input. This debounced input will ignore pulses of less than 1 ms and is guaranteed to respond to pulses greater than 20 ms.
TD	Time Delay Set allows the user to select the maximum amount of time the ADM1232 will allow the \$\overline{STROBE}\$ input to remain inactive (i.e., \$\overline{STROBE}\$ is not receiving any high-to-low transitions), without forcing the ADM1232 to generate a RESET pulse. (See \$\overline{STROBE}\$ specifications, Figure 4 and the note on \$\overline{STROBE}\$ timeout selection.)
TOLERANCE	Tolerance Input. This input will determine how much the supply voltage will be allowed to decrease (as a percentage tolerance) before a RESET is asserted. Connect to $V_{\rm CC}$ for 10% and GND for 5%.
GND	0 V ground reference for all signals.
RESET	Active high logic output. Will be asserted when: 1. V _{CC} decreases below the amount specified by the TOLERANCE input or, 2. PB RESET is forced low or, 3. If there are no high-to-low transitions within the limits set by TD at STROBE or, 4. During power-up.
RESET	Inverse of RESET, with an open drain output.
STROBE	The STROBE input is used to monitor the activity of a microprocessor. If there are no high-to-low transitions within the time specified by TD, a reset will be asserted.
V_{CC}	Power supply input +5 V.

PIN CONFIGURATIONS



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ADM1232

CIRCUIT INFORMATION

PB RESET

The PB RESET input makes it possible to manually reset a system using either a standard push-button switch or a logic low input. An internal debounce circuit provides glitch immunity when used with a switch, reducing the effects of glitches on the line. The debounce circuit is guaranteed to cause the ADM1232 to assert a reset if PB RESET is brought low for more than 20 ms and is guaranteed to ignore low inputs of less than 1 ms.

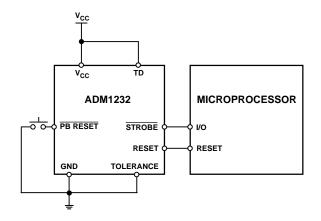


Figure 2. Typical Push Button Reset Application

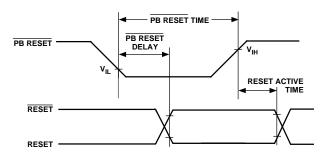


Figure 3. PB RESET

STROBE Timeout Selection

TD or time delay set is used to set the Strobe Timeout Period. The Strobe Timeout Period is defined as being the maximum time between high-to-low transitions (Figure 4) that \$\overline{STROBE}\$ will accept before a reset will be asserted. The Strobe timeout settings are listed in Table I.

Table I.

Condition	Min	Тур	Max	Units
TD = 0 V	62.5	150	250	ms
TD = Floating	250	600	1000	ms
$TD = V_{CC}$	500	1200	2000	ms

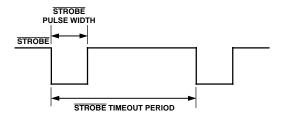


Figure 4. STROBE Parameters

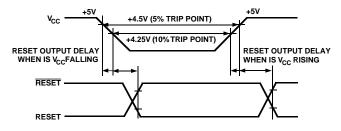


Figure 5. Reset Output Delay

TOLERANCE

The TOLERANCE input is used to determine the level V_{CC} can vary below 5 V without the ADM1232 asserting a reset. Connecting TOLERANCE to ground will select a –5% tolerance level and will cause the ADM1232 to generate a reset if V_{CC} falls below 4.75 V (typical). If TOLERANCE is connected to V_{CC} a –10% tolerance level is selected and will cause the ADM1232 to generate a reset if V_{CC} falls below 4.5 V (typical). Check the parameters for the V_{CC} trip point in the ADM1232 Specifications for more information.

RESET AND RESET OUTPUTS

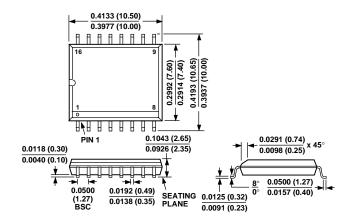
While RESET is capable of sourcing and sinking current, RESET is an open drain MOSFET which sinks current only. Therefore, it is necessary to pull this output high.

REV. B _5_

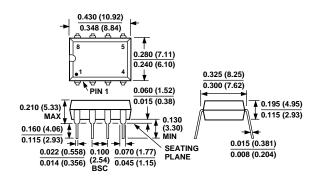
OUTLINE DIMENSIONS

Dimensions shown in inches and (mm).

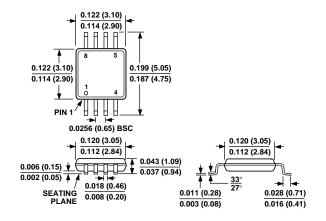
16-Lead Wide SOIC (R-16)



8-Lead PDIP (N-8)



8-Lead microSOIC (RM-8)



8-Lead Narrow SOIC (R-8)

